- Designed for Complementary Use with BDW64, BDW64A, BDW64B, BDW64C and BDW64D
- 60 W at 25°C Case Temperature
- 6 A Continuous Collector Current
- Minimum h_{FE} of 750 at 3 V, 2 A

TO-220 PACKAGE (TOP VIEW) B 1 C 2 B 3

Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
	BDW63		45	
	BDW63A		60	
Collector-base voltage (I _E = 0)	BDW63B	V _{CBO}	80	V
	BDW63C		100	
	BDW63D		120	
	BDW63		45	
	BDW63A		60	
Collector-emitter voltage (I _B = 0) (see Note 1)	BDW63B	V_{CEO}	80	V
	BDW63C		100	
	BDW63D		120	
Emitter-base voltage		V _{EB}	5	V
Continuous collector current		I _C	6	Α
Continuous base current	I _B	0.1	Α	
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)	P _{tot}	60	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note	P _{tot}	2	W	
Unclamped inductive load energy (see Note 4)	½LI _C ²	50	mJ	
Operating junction temperature range	T _j	-65 to +150	°C	
Operating temperature range	T _{stg}	-65 to +150	°C	
Operating free-air temperature range	T _A	-65 to +150	°C	

NOTES: 1. These values apply when the base-emitter diode is open circuited.

- 2. Derate linearly to 150°C case temperature at the rate of 0.48 W/°C.
- 3. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.
- This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH, I_{B(on)} = 5 mA, R_{BE} = 100 Ω, V_{BE(off)} = 0, R_S = 0.1 Ω, V_{CC} = 20 V.



BDW63, BDW63A, BDW63B, BDW63C, BDW63D NPN SILICON POWER DARLINGTONS

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electrical characteristics at 25°C case temperature (unless otherwise noted)

	PARAMETER		TEST	CONDITIONS		MIN	TYP	MAX	UNIT
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C = 30 mA	I _B = 0	(see Note 5)	BDW63 BDW63A BDW63B BDW63C	45 60 80 100			V
I _{CEO}	Collector-emitter cut-off current	$V_{CE} = 50 \text{ V}$ $V_{CE} = 60 \text{ V}$	$I_{B} = 0$		BDW63D BDW63A BDW63B BDW63C BDW63D	120		0.5 0.5 0.5 0.5 0.5	mA
І _{СВО}	Collector cut-off current	$V_{CB} = 100 \text{ V}$ $V_{CB} = 120 \text{ V}$ $V_{CB} = 45 \text{ V}$ $V_{CB} = 60 \text{ V}$ $V_{CB} = 80 \text{ V}$ $V_{CB} = 100 \text{ V}$	E = 0 E = 0	$T_{C} = 150^{\circ}\text{C}$	BDW63 BDW63A BDW63B BDW63C BDW63D BDW63 BDW63A BDW63A BDW63B BDW63C BDW63D			0.2 0.2 0.2 0.2 0.2 5 5 5	mA
I _{EBO}	Emitter cut-off current	V _{EB} = 5 V	I _C = 0	-				2	mA
h _{FE}	Forward current transfer ratio	$V_{CE} = 3 V$ $V_{CE} = 3 V$	$I_C = 2 A$ $I_C = 6 A$	(see Notes 5 and 6)		750 100		20000	
$V_{\text{BE(on)}}$	Base-emitter voltage	V _{CE} = 3 V	I _C = 2 A	(see Notes 5 and 6)				2.5	V
V _{CE(sat)}	Collector-emitter saturation voltage	$I_B = 12 \text{ mA}$ $I_B = 60 \text{ mA}$	$I_C = 2 A$ $I_C = 6 A$	(see Notes 5 and 6)				2.5 4	V
V _{EC}	Parallel diode forward voltage	I _E = 6 A	I _B = 0					3.5	V

NOTES: 5. These parameters must be measured using pulse techniques, t_p = 300 μ s, duty cycle \leq 2%.

thermal characteristics

PARAMETER	MIN	TYP	MAX	UNIT
R _{0JC} Junction to case thermal resistance			2.08	°C/W
R _{0JA} Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

PA	ARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
t _{on} T	urn-on time	I _C = 3 A	$I_{B(on)} = 12 \text{ mA}$	$I_{B(off)} = -12 \text{ mA}$		1		μs
t _{off} T	urn-off time	$V_{BE(off)} = -4.5 \text{ V}$	$R_L = 10 \Omega$	$t_p = 20 \ \mu s, \ dc \le 2\%$		5		μs

[†] Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

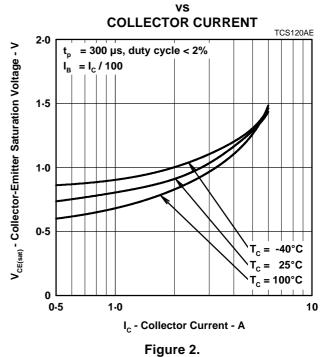
PRODUCT INFORMATION

^{6.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

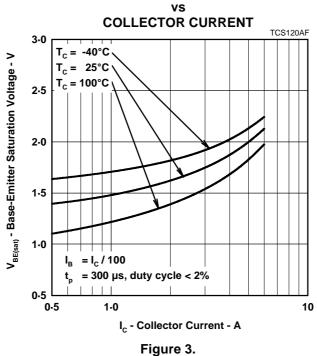
TYPICAL CHARACTERISTICS

TYPICAL DC CURRENT GAIN COLLECTOR CURRENT TCS120AD 40000 $T_c = -40^{\circ}C$ 25°C $T_c = 100$ °C h_{FE} - Typical DC Current Gain 10000 1000 3 V $V_{CE} =$ = 300 µs, duty cycle < 2% 100 0.5 1.0 10 Ic - Collector Current - A Figure 1.

COLLECTOR-EMITTER SATURATION VOLTAGE

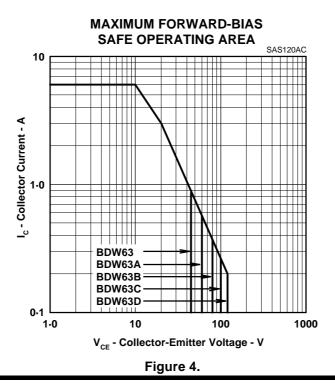


BASE-EMITTER SATURATION VOLTAGE



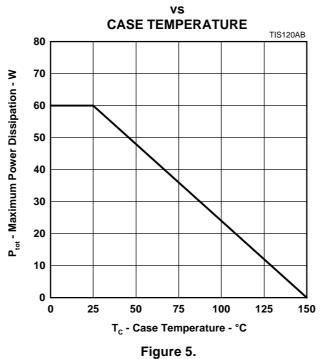
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MAXIMUM SAFE OPERATING REGIONS



THERMAL INFORMATION

MAXIMUM POWER DISSIPATION



PRODUCT INFORMATION

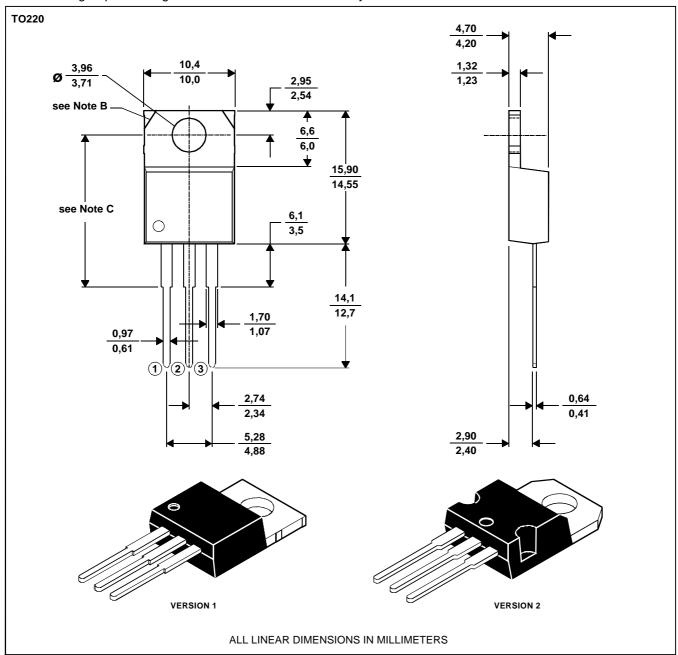
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MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

- B. Mounting tab corner profile according to package version.
- C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm.

MDXXBE

PRODUCT INFORMATION

BDW63, BDW63A, BDW63B, BDW63C, BDW63D NPN SILICON POWER DARLINGTONS

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